



Surge arrester

2-electrode arrester

Series/Type: S30-A300X
Ordering code: B88069X5531T203
Version/Date: Issue 05 / 2014-02-27

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Description

The S30-series has been especially designed to meet data transmission protection requirements. The optimized design features a high level of protection against fast rising transients usually caused by lightning disturbances. For use in high frequency data lines, the series offers ultra low capacitances and shows only marginally signal losses up to high frequencies. The devices are extremely reliable and are able to withstand high surge currents without destruction.

Features

- Very small size (EIA 1812)
- Short response time
- High current handling capability
- Stable performance over service life
- Ultra low capacitance and insertion loss
- High insulation resistance
- Excellent SMD handling
- RoHS-compatible

Applications

Telecommunication:

- Ethernet, PoE, xDSL
- Cable modem, splitters, line cards
- Wireless antenna protection

Others:

- CCTV
- Switching power supply

Product characteristics

Physical dimensions (length x width x height)	0.18 x 0.12 x 0.10	in
	4.5 x 3.2 x 2.7	mm
	EIA 1812 / 4532 metric	
Weight	~ 0.2	g
Operating temperature	-40 ... +90	°C
Recommended storage ¹⁾ - temperature - humidity - period	+5 ... +35 45 ... 80 ≤ 2	°C % years
Climatic category (IEC 60068-1)	40/ 90/ 21	
Moisture sensitivity level ²⁾	1	
Marking, black positive	▲IY I - Nominal voltage (I ≙ 300 V) Y - Year of production (last digit)	
Certifications	UL 497B (E163070)	

Notes:

¹⁾ Specified in terms of corrosion against Sn-plating

²⁾ Tests according to JEDEC J-STD-020

Electrical specifications and stress test methods

Nominal DC spark-over voltage ^{3) 4)}	300	V
Tolerance	± 25	%
Min.	225	V
Max.	375	V
Impulse spark-over voltage		
at 100 V/μs	- for 99% of measured values - typical values of distribution	< 700 < 650
		V V
at 1 kV/μs	- for 99% of measured values - typical values of distribution	< 850 < 800
		V V
Service life ^{5) 6)}		
10 operations	50 Hz, 1 s	2
		A
300 operations	8/20 μs	100
		A
10 operations [5x (+) & 5x (-)]	8/20 μs	1
		kA
100 operations [50x (+) & 50x (-)]	10/1000 μs	10
		A
Insulation resistance at 100 V _{DC}	> 1	GΩ
Capacitance at 1 MHz	< 0.8	pF
Arc voltage at 1 A	~ 10	V
Glow to arc transition current	< 0.4	A
Glow voltage	~ 55	V

³⁾ At delivery AQL 0.65 level II, DIN ISO 2859

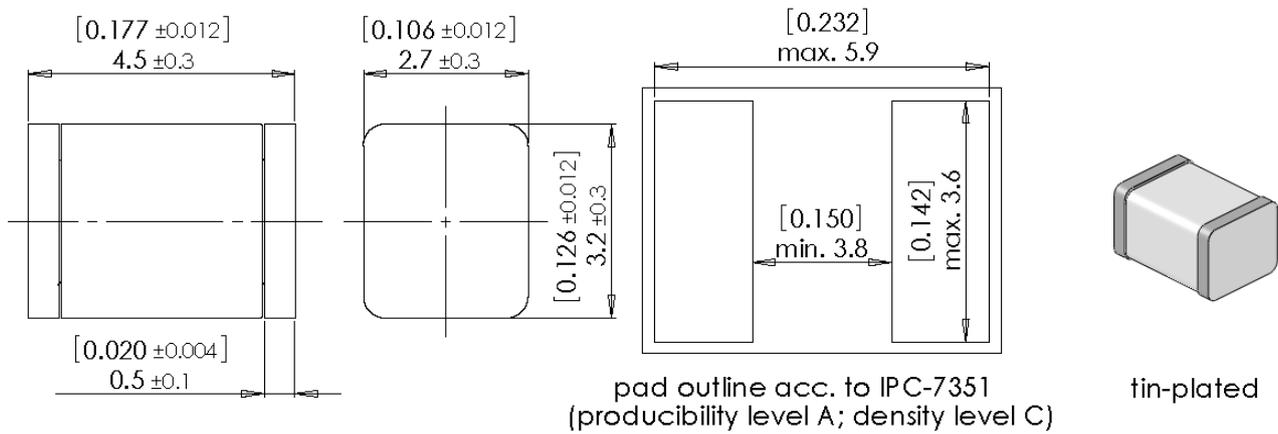
⁴⁾ In ionized mode

⁵⁾ Tests according to ITU-T Rec. K. 12 and UL 497B

⁶⁾ Electrical specifications may vary after stress tests

Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21; IEC 61643-311 and IEC 61663-2.

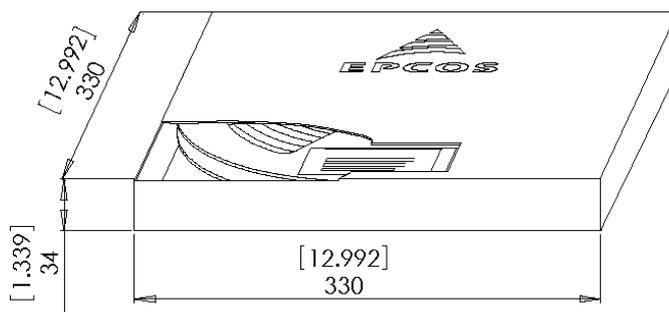
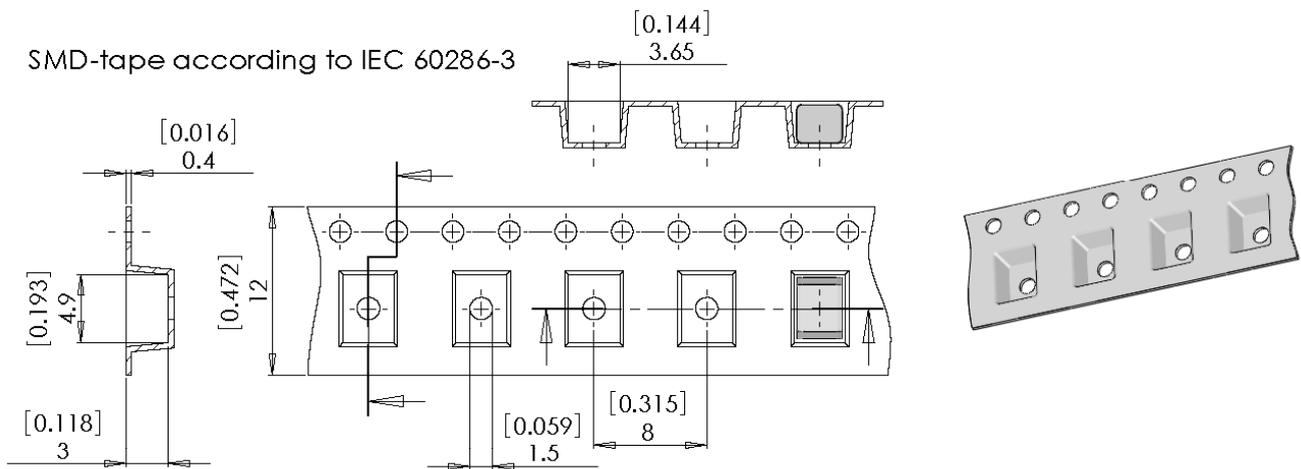
Dimensional drawing in mm



Ordering code and packing advice

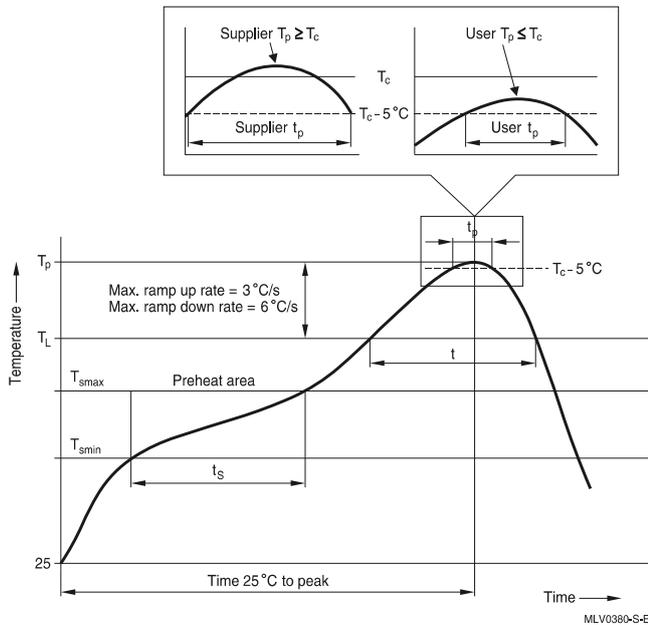
B88069X5531T203 = 2000 pcs. on SMD-tape

SMD-tape according to IEC 60286-3



Soldering parameters

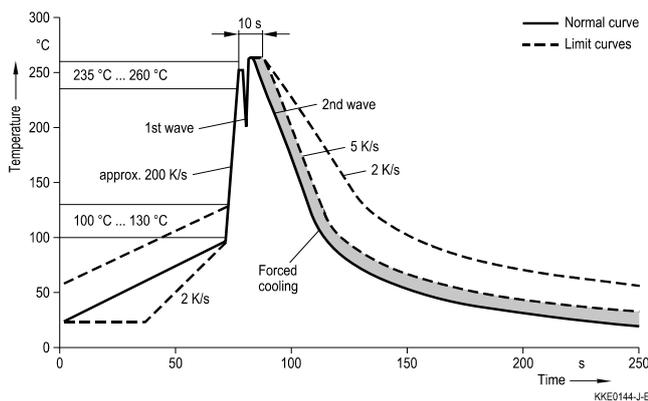
Reflow soldering



Reflow profile features		Sn- Pb eutectic assembly	Pb-free assembly
Preheat and soak			
- Temperature min	T_{smin}	100 °C	150 °C
- Temperature max	T_{smax}	150 °C	200 °C
- Time	t_{smin} to t_{smax}	60 ... 120 s	60 ... 180 s
Average ramp-up rate	T_{smax} to T_p	max. 3 °C/ s	max. 3 °C/ s
Liquidous temperature	T_L	183 °C	217 °C
Time at liquidous	t_L	60 ... 150 s	60 ... 150 s
Peak package body temperature *, Classification temperature **	T_p, T_c	220 ... 235 °C **	245 ... 260 °C **
Time (t_p) ** within 5 °C of the specified classification temperature (T_c)		20 s ***	30 s ***
Average ramp-down rate	T_p to T_{smax}	max. 6 °C/ s	max. 6 °C/ s
Time 25 °C to peak temperature		max. 6 min	max. 8 min

* = Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
 ** = For details please refer to JEDEC J-STD-020D.
 *** = Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

Wave soldering



Wave profile features	Pb-free assembly
Solder	Sn 95.5 / Ag 3.8 / Cu 0.7
Solder bath temperature	263 (±3) °C
Dwell time	< 3 s

Soldering profile applied to a single soldering process.

Cautions and warnings

- Surge arresters must not be operated directly in power supply networks.
- Surge arresters may become hot in the event of longer periods of current stress (danger of burning). In the event of thermal overload the connectors may fail or the component may be destroyed.
- Surge arresters must be handled with care and must not be dropped.
- Damaged surge arresters must not be re-used.

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